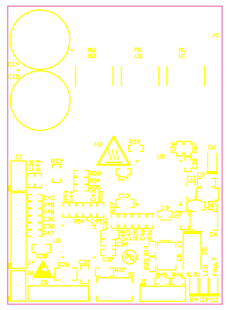
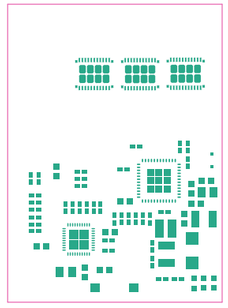
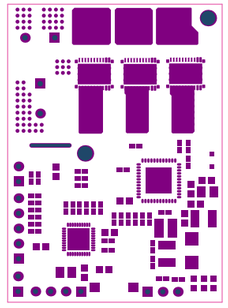


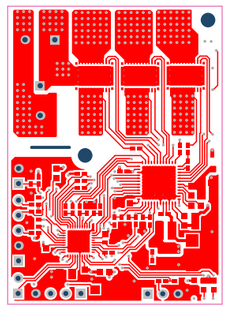
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01485	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01485		
Top Overlay	GENERATED : 8/1/2017 12:06:34 PM		TEXAS INSTRUMENTS



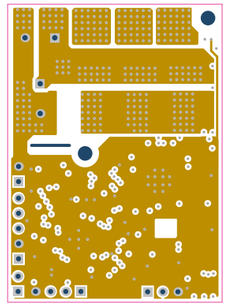
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01485	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Paste	TID #: 01485		
Top Paste	GENERATED : 8/1/2017 12:06:35 PM		TEXAS INSTRUMENTS



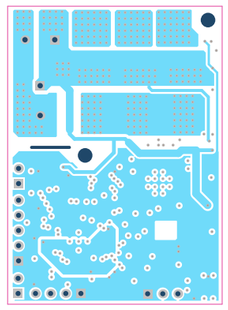
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01485	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01485		
Top Solder Mask	GENERATED : 8/1/2017 12:06:36 PM		TEXAS INSTRUMENTS



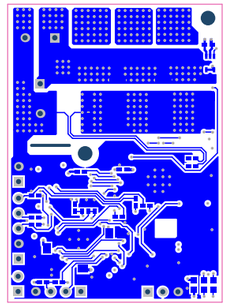
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01485	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: 01485		
Top Layer	GENERATED : 8/1/2017 12:06:37 PM		TEXAS INSTRUMENTS



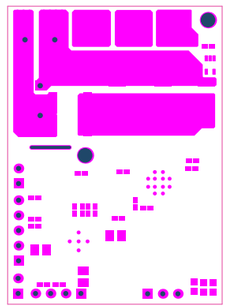
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01485	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = GND	TID #: 01485		
GND	GENERATED : 8/1/2017 12:06:38 PM		TEXAS INSTRUMENTS



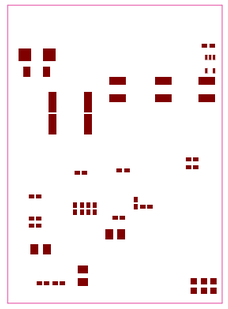
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01485	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = PWR	TID #: 01485		
PWR	GENERATED : 8/1/2017 12:06:39 PM		TEXAS INSTRUMENTS



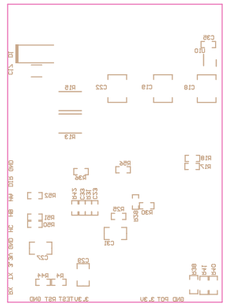
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01485	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: 01485		
Bottom Layer	GENERATED : 8/1/2017 12:06:40 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01485	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01485		
Bottom Solder Mask	GENERATED : 8/1/2017 12:06:41 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01485	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Paste	TID #: 01485		
Bottom Paste	GENERATED : 8/1/2017 12:06:41 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01485	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 01485		
Bottom Overlay	GENERATED : 8/1/2017 12:06:42 PM		TEXAS INSTRUMENTS

Layer Stack Up Detail for: TIDA-01485-E1

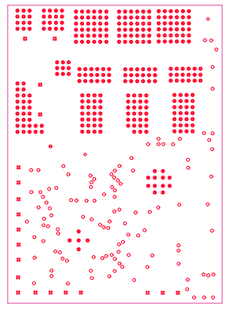
Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	2.8mil	FR-4 High Tg
GND	(.G1)	2.8mil	FR-4 High Tg
PWR	(.G2)	2.8mil	FR-4 High Tg
Bottom Layer	(.GBL)	2.8mil	FR-4 High Tg
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
36mm X 50mm

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 7 MIL
MIN. VIA DRILL SIZE: 7.87 MIL
MINIMUM ANNULAR RING 5.91 MIL EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 63 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [X] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [X] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER _____
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS: VIA TENTING: YES [X] NO [ ]
MICROSECTION: [ ] YES IMPEDANCE CONTROL: YES [ ] NO [X]
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



Symbol	Count	Hole Size	Hole Length	Routed Path Length	Plated	Hole Type
◎	1	20.00mil (0.508mm)	270.00mil (6.858mm)	250.00mil (6.350mm)	NPTH	Slot
◇	2	96.46mil (2.450mm)	-	-	NPTH	Round
▣	4	35.43mil (0.900mm)	-	-	PTH	Round
⊠	16	33.46mil (0.850mm)	-	-	PTH	Round
○	115	10.00mil (0.254mm)	-	-	PTH	Round
✪	328	7.87mil (0.200mm)	-	-	PTH	Round
	466 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Drill Table

FOR 7.874MIL DRILL +0/-7.874MIL
FOR 10MIL DRILL +0/-10MIL
FOR PTH DRILL +/-3MIL
FOR NPTH DRILL +/-2MIL

NOTE :
Only 10 mil vias are tented , others are not tented.

TEXAS INSTRUMENTS

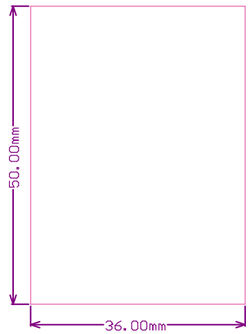
PROJECT TITLE:
18V/1kW, power stage for brushless motor

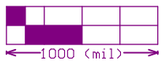
DESIGNED FOR:
Public Release

FILE NAME:
TIDA-01485.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01485	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01485		
Drill Drawing	GENERATED : 8/1/2017 12:06:45 PM		TEXAS INSTRUMENTS

ENGINEER: Manu Balakrishnan
LAYOUT BY: Avinash N
SCALE: 1.00
ALTIUM DESIGNER VERSION: 16.1.9.221





ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01485	REV: E2	SVN REV: Not In VersionControl
LAYER NAME =	TID #: 01485		
Board Dimensions	GENERATED : 8/1/2017 12:06:47 PM		TEXAS INSTRUMENTS

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